High Speed Infrared Emitting Diodes, 940 nm, Surface Emitter Technology

DESCRIPTION
As part of the SurfLight™ portfolio, the VSMY2940 series are infrared, 940 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS
• Miniature light barrier
• Photointerrupters
• Optical switch
• Emitter source for proximity sensors

FEATURES
• Package type: surface-mount
• Package form: GW, RGW
• Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
• Peak wavelength: \( \lambda_p = 940 \) nm
• AEC-Q101 qualified
• High radiant power
• Very high radiant intensity
• Angle of half intensity: \( \varphi = \pm 10^\circ \)
• Suitable for high pulse current operation
• Terminal configurations: gullwing or reverse gullwing
• Package matches with detector VEMD2000X01 series
• Floor life: 4 weeks, MSL 2a, according to J-STD-020
• Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

PRODUCT SUMMARY

<table>
<thead>
<tr>
<th>COMPONENT</th>
<th>I_e (mW/sr)</th>
<th>( \varphi ) (deg)</th>
<th>( \lambda_p ) (nm)</th>
<th>( t_r ) (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td>VSMY2940RGX01</td>
<td>145</td>
<td>± 10</td>
<td>940</td>
<td>10</td>
</tr>
<tr>
<td>VSMY2940GX01</td>
<td>145</td>
<td>± 10</td>
<td>940</td>
<td>10</td>
</tr>
</tbody>
</table>

Note
• Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>ORDERING CODE</th>
<th>PACKAGING</th>
<th>REMARKS</th>
<th>PACKAGE FORM</th>
</tr>
</thead>
<tbody>
<tr>
<td>VSMY2940RGX01</td>
<td>Tape and reel</td>
<td>MOQ: 6000 pcs, 6000 pcs/reel</td>
<td>Reverse gullwing</td>
</tr>
<tr>
<td>VSMY2940GX01</td>
<td>Tape and reel</td>
<td>MOQ: 6000 pcs, 6000 pcs/reel</td>
<td>Gullwing</td>
</tr>
</tbody>
</table>

Note
• MOQ: minimum order quantity
ABSOLUTE MAXIMUM RATINGS (T_{\text{amb}} = 25 °C, unless otherwise specified)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITION</th>
<th>SYMBOL</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse voltage</td>
<td></td>
<td>V_R</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>Forward current</td>
<td></td>
<td>I_F</td>
<td>100</td>
<td>mA</td>
</tr>
<tr>
<td>Peak forward current</td>
<td>t_p/T = 0.5, t_p = 100 μs</td>
<td>I_{FM}</td>
<td>200</td>
<td>mA</td>
</tr>
<tr>
<td>Surge forward current</td>
<td>t_p = 100 μs</td>
<td>I_{FSM}</td>
<td>1</td>
<td>A</td>
</tr>
<tr>
<td>Power dissipation</td>
<td></td>
<td>P_V</td>
<td>170</td>
<td>mW</td>
</tr>
<tr>
<td>Junction temperature</td>
<td></td>
<td>T_J</td>
<td>100</td>
<td>°C</td>
</tr>
<tr>
<td>Operating temperature range</td>
<td></td>
<td>T_{amb}</td>
<td>-40 to +85</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature range</td>
<td></td>
<td>T_{stg}</td>
<td>-40 to +100</td>
<td>°C</td>
</tr>
<tr>
<td>Soldering temperature</td>
<td>According to Fig. 10, J-STD-020</td>
<td>T_{sd}</td>
<td>260</td>
<td>°C</td>
</tr>
<tr>
<td>Thermal resistance junction-to-ambient</td>
<td>J-STD-051, soldered on PCB</td>
<td>R_{th JA}</td>
<td>250</td>
<td>K/W</td>
</tr>
</tbody>
</table>

**BASIC CHARACTERISTICS (T_{\text{amb}} = 25 °C, unless otherwise specified)**

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITION</th>
<th>SYMBOL</th>
<th>MIN.</th>
<th>TYP.</th>
<th>MAX.</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Forward voltage</td>
<td>I_F = 100 mA, t_p = 20 ms</td>
<td>V_F</td>
<td>-</td>
<td>1.4</td>
<td>1.8</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>I_F = 1 A, t_p = 100 μs</td>
<td>V_F</td>
<td>-</td>
<td>2.5</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>Temperature coefficient of V_F</td>
<td>I_F = 100 mA</td>
<td>T_{KVF}</td>
<td>-</td>
<td>-0.7</td>
<td>-</td>
<td>mV/K</td>
</tr>
<tr>
<td>Reverse current</td>
<td>I_R</td>
<td></td>
<td>Not designed for reverse operation</td>
<td>-</td>
<td>μA</td>
<td></td>
</tr>
<tr>
<td>Junction capacitance</td>
<td>V_R = 0 V, f = 1 MHz, E = 0 mW/cm²</td>
<td>C_J</td>
<td>-</td>
<td>55</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td>Radiant intensity</td>
<td>I_F = 100 mA, t_p = 20 ms</td>
<td>I_e</td>
<td>75</td>
<td>145</td>
<td>215</td>
<td>mW/sr</td>
</tr>
<tr>
<td></td>
<td>I_F = 1 A, t_p = 100 μs</td>
<td>I_e</td>
<td>-</td>
<td>1000</td>
<td>-</td>
<td>mW/sr</td>
</tr>
<tr>
<td>Radiant power</td>
<td>I_F = 100 mA, t_p = 20 ms</td>
<td>\phi_e</td>
<td>55</td>
<td>-</td>
<td>-</td>
<td>mW</td>
</tr>
<tr>
<td>Temperature coefficient of radiant power</td>
<td>I_F = 100 mA</td>
<td>T_{K\phi_e}</td>
<td>-</td>
<td>-0.2</td>
<td>-</td>
<td>%/K</td>
</tr>
<tr>
<td>Angle of half intensity</td>
<td>\varphi</td>
<td></td>
<td>\pm 10</td>
<td>-</td>
<td>-</td>
<td>deg</td>
</tr>
<tr>
<td>Peak wavelength</td>
<td>I_F = 100 mA</td>
<td>\lambda_p</td>
<td>920</td>
<td>940</td>
<td>960</td>
<td>nm</td>
</tr>
<tr>
<td>Spectral bandwidth</td>
<td>I_F = 100 mA</td>
<td>\Delta\lambda</td>
<td>50</td>
<td>-</td>
<td>-</td>
<td>nm</td>
</tr>
<tr>
<td>Temperature coefficient of \lambda_p</td>
<td>I_F = 100 mA</td>
<td>T_{K\lambda_p}</td>
<td>-</td>
<td>0.25</td>
<td>-</td>
<td>nm/K</td>
</tr>
<tr>
<td>Rise time</td>
<td>I_F = 100 mA, 10 % to 90 %</td>
<td>t_r</td>
<td>-</td>
<td>10</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>Fall time</td>
<td>I_F = 100 mA, 10 % to 90 %</td>
<td>t_f</td>
<td>-</td>
<td>10</td>
<td>-</td>
<td>ns</td>
</tr>
</tbody>
</table>
BASIC CHARACTERISTICS  \((T_{\text{amb}} = 25 \, ^\circ\text{C}, \text{unless otherwise specified})\)

- **Fig. 3 - Forward Current vs. Forward Voltage**
- **Fig. 4 - Relative Forward Voltage vs. Ambient Temperature**
- **Fig. 5 - Relative Radiant Intensity vs. Forward Current**
- **Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature**
- **Fig. 7 - Relative Radiant Intensity vs. Wavelength**
- **Fig. 8 - Relative Radiant Intensity vs. Angular Displacement**
SOLDER PROFILE

![Solder Profile Graph]

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

**FLOOR LIFE**

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: \( T_{\text{amb}} < 30 ^\circ C, \text{RH} < 60 \% \)

Moisture sensitivity level 2a, according to J-STD-020.

**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions

192 h at 40 °C (+ 5 °C), RH < 5 %.

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**PACKAGE DIMENSIONS** in millimeters: **VSMY2940RGX01**

![Package Dimensions Diagram]

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**Drawing-No.:** 6.544-5391.03-4

**Issue:** 2; 19.09.14

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For technical questions, contact: emittertechsupport@vishay.com

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PACKAGE DIMENSIONS in millimeters: VSMY2940GX01

Drawing-No.: 6.544-5383.03-4
Issue: 2; 19.09.14
TAPING AND REEL DIMENSIONS in millimeters: VSMY2940RGX01

Leader and trailer tape

Terminal position in tape

Device | Lead I | Lead II
-------|--------|--------
VEMT2000 | Collector | Emitter
VEMT2500 | Cathode | Anode
VEMD2000 | | 
VEMD2500 | | 
VSMB2000 | | 
VSMG2000 | | 
VSMF2890RG | | 
VSMY2850RG | Anode | Cathode
VSMY2940RG | | 

Drawing-No.: 9.800-5100.01-4
Issue: 4; 19.09.14
TAPPING AND REEL DIMENSIONS in millimeters: VSMY2940GX01

Device | Lead I  | Lead II |
-------|---------|---------|
VSMB2020 | Cathode | Anode   |
VSMG2020 |         |         |
VEMD2020 |         |         |
VEMD2520 |         |         |
VSMF2890G |       |         |
VEMT2020 | Collector | Emitter |
VEMT2520 |         |         |
VSMY2850G | Anode | Cathode |
VSMY2940G |         |         |

Drawing-No.: 9.800-5091.01-4
Issue: S; 19.09.14
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